



Procedure 96025			
Title:	LIS-1024x-LG / ELIS-1024x-LG /RPLIS-2048x-LG		
	Handling Procedure		
Rev:	C	ECN/Rel Applied:	ECN00093

Purpose: This document contains the procedure for handling the LIS-1024x-LG, ELIS-1024x-LG, and RPLIS-2048x-LG image sensors (any version) that have been removed from the vacuum-sealed DryPak bag for more than 168 hours to prevent part damage during the solder re-flow process

Procedure:

- 1) If the sensors were provided to the customer in a JEDEC tray, be sure that the tray is rated to 150° C as marked on the tray. If the sensors were not provided in the JEDEC trays or the trays are not rated for 150° C then the sensor are to be placed onto metal trays, or something similar, which will not melt at 125° C or contaminate the sensors. The sensors should be baked at 125° C for a minimum of 8 hours, with a recommended time of 12 hours. This will prevent part damage during the solder re-flow process due to moisture collection during shipping.
- 2) Sensor must be re-flowed within 168 hours of baking or of opening the DryPak bag. If devices are left open greater than 168 hours the baking process must be repeated.
- 3) All standard ESD protection procedures should be maintained when handling devices.

NOTE: THIS PROCEDURE TO ACCOMPANY EACH SHIPMENT.